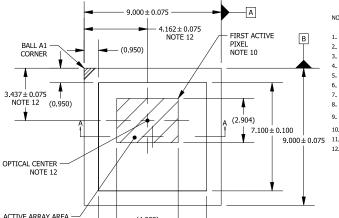


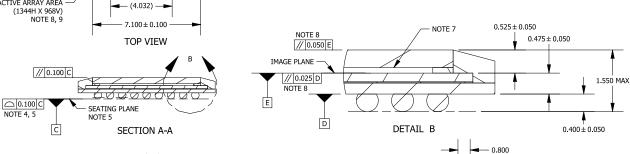
IBGA80 9x9 CASE 503BM

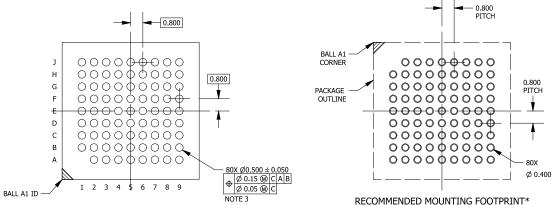
ISSUE D

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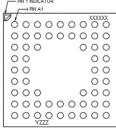
- 1 DIMENSIONING AND TOLERANCING PER ASME Y14 5M 1994
- CONTROLLING DIMENSION: MILLIMETERS [mm].
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C. THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ± 0.5°.
- 10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- PACKAGE CENTER (X, Y) = (0.000, 0.000).
 OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.338, 1.063).





BOTTOM VIEW GENERIC MARKING DIAGRAM*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



XXXX = Specific Device Code = Year

ZZZ = Assembly Lot

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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